

N-Channel 60 V (D-S) MOSFET

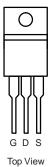
PRODUCT SUMMARY				
V _{DS} (V)	60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.003			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.009			
I _D (A)	210			
Configuration	Single			

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Package with Low Thermal Resistance
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC









ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V_{DS}	60	V		
Gate-Source Voltage		V _{GS} ± 20		V		
Continuous Drain Current	T _C = 25 °C	1	210			
	T _C = 125 °C	- I _D	120 ^a			
Continuous Source Current (Diode Conduction) ^a	I _S	120 ^a	Α			
Pulsed Drain Current ^b		I _{DM}	480			
Single Pulse Avalanche Current	. 0.1!!	I _{AS}	75			
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	281	mJ		
Maximum Power Dissipation ^b	T _C = 25 °C	D	375	W		
	T _C = 125 °C	P_{D}	125	VV		
Operating Junction and Storage Temperature Range	je	T _J , T _{stg}	- 55 to + 175	°C		

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount ^c	R_{thJA}	40	°C/W	
Junction-to-Case (Drain)		R_{thJC}	0.4	C/ VV	

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.



PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static	1			l.		·		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0$, $I_D = 250 \mu A$		60	-	-		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$		-	3.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA	
		V _{GS} = 0 V	V _{DS} = 60 V	-	-	1.0		
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V	V _{DS} = 60 V, T _J = 125 °C	-	-	50	μΑ	
		V _{GS} = 0 V	V _{DS} = 60 V, T _J = 175 °C	-	-	350		
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	V _{DS} ≥ 5 V	120	-	-	Α	
		V _{GS} = 10 V	I _D = 30 A	-	0.003	-	Ω	
Dunin Course On Otata Basistanas		V _{GS} = 10 V	I _D = 30 A, T _J = 125 °C	-	0.006	-		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 30 A, T _J = 175 °C	-	0.008	-		
		V _{GS} = 4.5 V	I _D = 20 A	-	0.009	-		
Forward Transconductanceb	9 _{fs}	V _{DS} = 15 V, I _D = 30 A		-	109	-	S	
Dynamic ^b								
Input Capacitance	C _{iss}		V _{DS} = 25 V, f = 1 MHz	-	9300	-	pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$		-	1000	-		
Reverse Transfer Capacitance	C _{rss}]		-	750	-		
Total Gate Charge ^c	Qg			-	180	-	nC	
Gate-Source Charge ^c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 30 \text{ V}, I_{D} = 110 \text{ A}$	-	24.7	-		
Gate-Drain Charge ^c	Q _{gd}	1		-	50.4	-		
Gate Resistance	R _g	f = 1 MHz		0.5	1.1	1.6	Ω	
Turn-On Delay Time ^c	t _{d(on)}	$V_{DD} = 30 \text{ V, } R_L = 0.27 \Omega$ $I_D \cong 110 \text{ A, } V_{GEN} = 10 \text{ V, } R_g = 2.5 \Omega$		-	19	29	- ns	
Rise Time ^c	t _r			-	23	35		
Turn-Off Delay Time ^c	t _{d(off)}			-	83	125		
Fall Time ^c	t _f			-	35	53		
Source-Drain Diode Ratings and Char-	acteristics ^b	•			•			
Pulsed Current ^a	I _{SM}			-	-	480	Α	
Forward Voltage	V _{SD}	I _F = 100 A, V _{GS} = 0		-	0.9	1.5	V	

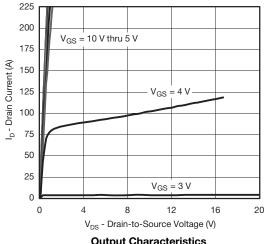
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

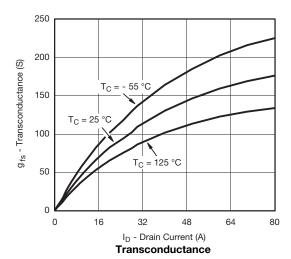
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

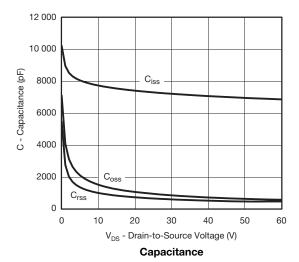


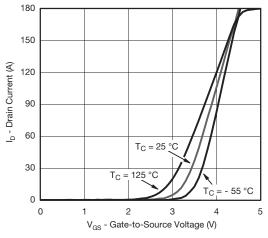
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



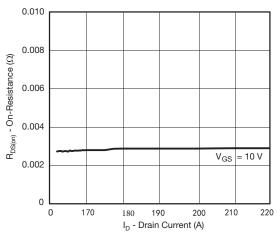
Output Characteristics



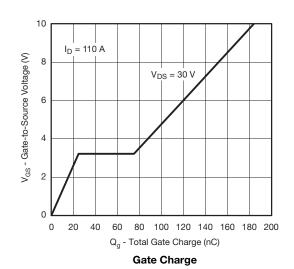




Transfer Characteristics

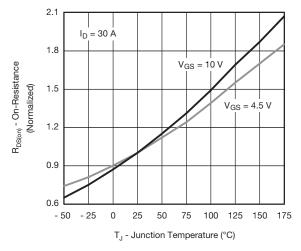


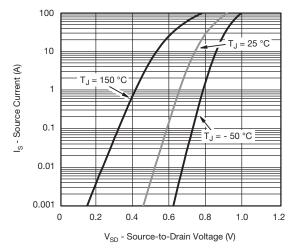
On-Resistance vs. Drain Current



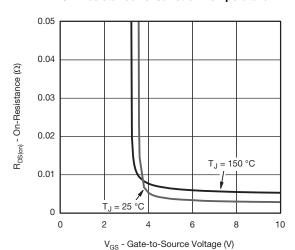


TYPICAL CHARACTERISTICS ($T_A = 25 \, ^{\circ}\text{C}$, unless otherwise noted)

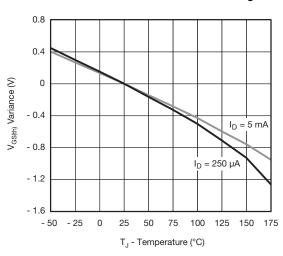




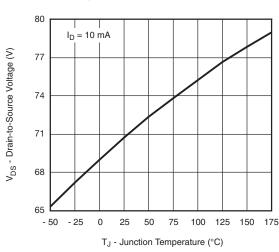
On-Resistance vs. Junction Temperature



Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage

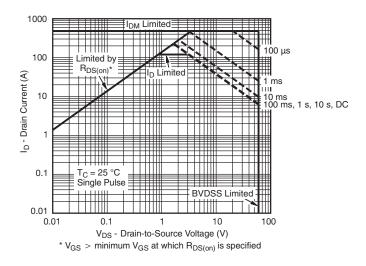


Threshold Voltage

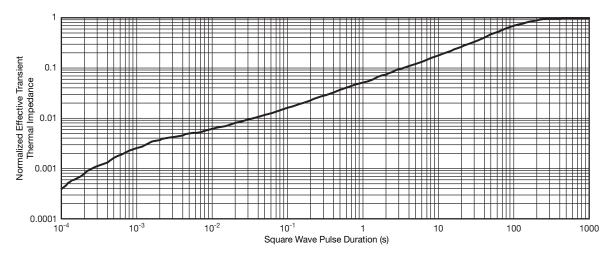
Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



Safe Operating Area

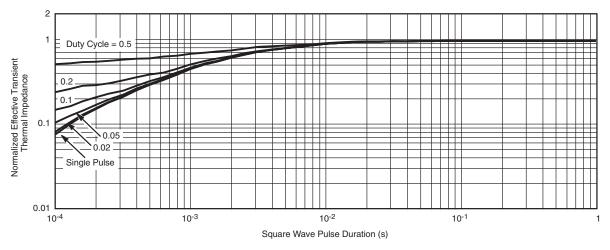


Normalized Thermal Transient Impedance, Junction-to-Ambient

服务热线:400-655-8788 5



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

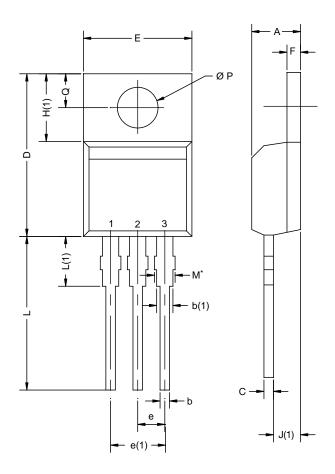
Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



TO-220AB



	MILLIN	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471					

Notes

 $^{^{\}star}$ M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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